

68V N-Channel Trench MOSFET(Preliminary)

General Description		Product Summary		
 Trench Power technology Low R_{DS(ON)} Low Gate Charge Optimized for fast-switching applications 			V_{DS} I _D (at V _{GS} =10V) R _{DS(ON)} (at V _{GS} =10V)	68V 135A < 5.0mΩ
 Applications Synchronous Rectification in DC/DC and AC/DC Converters Isolated DC/DC Converters in Telecom and Industrial 			100% UIS Tested	RoHS
TO-263 G D S		TO-220		
Part Number	Packa	ge Type	Form	Marking
TTB135N68A	TO-263		Tape&Reel	135N68A
TTP135N68A TO-		9-220	Tube	135N68A
Absolute Maximum Ra	tinas (T. =2	5ºC unless o	otherwise noted)	
Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	68	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current	T _C =25°C		105	A
Continuous Drain Current	T _C =100°C	- I _D	105	A
Pulsed Drain Current ^A		I _{DM}	405	А
Avalanche Current ^A		I _{AS}	44	А
Single Pulse Avalanche Energy	L =0.3mH ^A	E _{AS}	290	mJ
Power Dissipation ^C	T _C =25°C	P _D	160	W
$T_{c} = 100^{\circ}C$ Junction and Storage Temperature Range			80 -55 to 175	₩
Thermal Characteristics		T _J , T _{STG}	-55 10 175	0
		Symbol	Maximum	Units
Parameter			WIAAIIIIUIII	UIIIIS
	Steady State	D	0.05	
Maximum Junction-to-Case	Steady-State Steady-State	R _{ejc}	0.95	°C/W



Electric	al Characteristics(T _J =25°C ur	less otherwise i	noted)				
Symbol	Peremeter	Conditions		Value			Units
Symbol	Parameter			Min	Тур	Max	Units
STATIC P	ARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I _D =250µA,V _{GS} =0V		68			V
		$V_{DS} = 68V, V_{GS} = 0V$	T _J =25°C			1	
I _{DSS}	Zero Gate Voltage Drain Current		T _J =100°C			25	μA
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$				±100	nA
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$		2	3	4	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =30A			4.2	5	mΩ
g _{FS}	Forward Transconductance	V _{DS} = 5V, I _D =20A			30		S
V _{SD}	Diode Forward Voltage	I _S =20A, V _{GS} =0V				1	V
I _s	Maximum Body-Diode Continuous Current				105	А	
DYNAMIC	PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =30V, f =1MH _Z			6646		
C _{oss}	Output Capacitance				443		pF
C _{rss}	Reverse Transfer Capacitance				396		
SWITCHIN	NG PARAMETERS						
Q _g (10V)	Total Gate Charge				114		
Q_{gs}	Gate Source Charge	V _{GS} =10V,V _{DS} =30V,	V _{GS} =10V,V _{DS} =30V, I _D =30A		26		nC
Q_{gd}	Gate Drain Charge				34		
t _{D(on)}	Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 30V, I_{D} = 30A,$ $R_{G} = 3\Omega$			17		
t _r	Turn-On Rise Time				11		- ns
T _{D(off)}	Turn-Off Delay Time				55		
t _f	Turn-Off Fall Time				15		
t _{rr}	Body Diode Reverse Recovery Time				33		ns
Q _{rr}	Body Diode Reverse Recovery Charge	−I _F =20A, di/dt =100A/μs			51		nC

A. Single pulse width limited by maximum junction temperature.

- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)} = 175^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

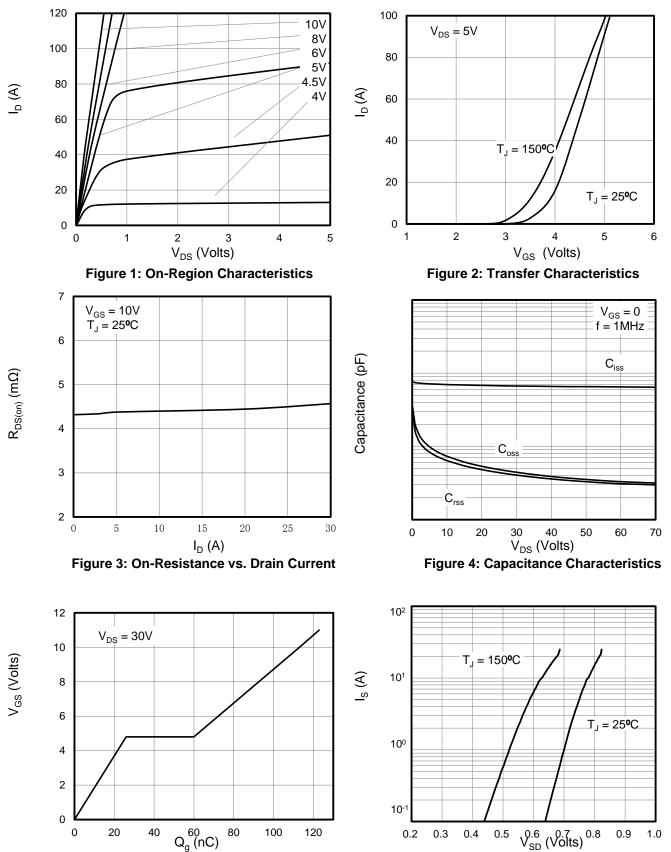
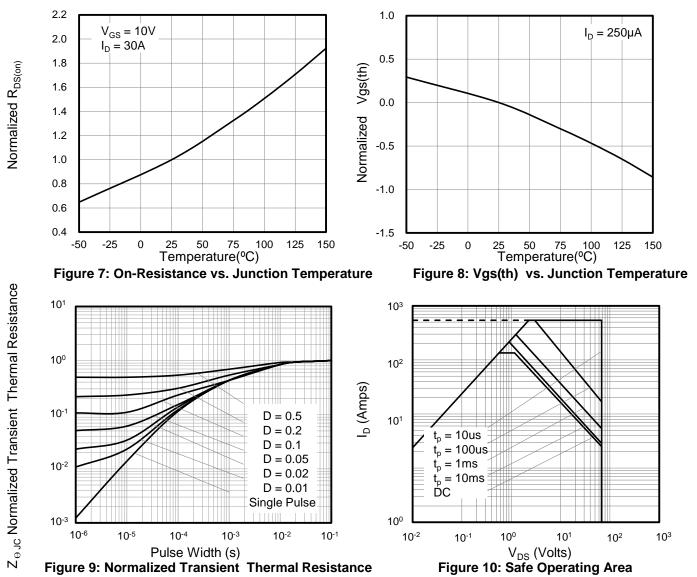


Figure 5: Gate Charge Characteristics

Figure 6: Body Diode Forward Voltage



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



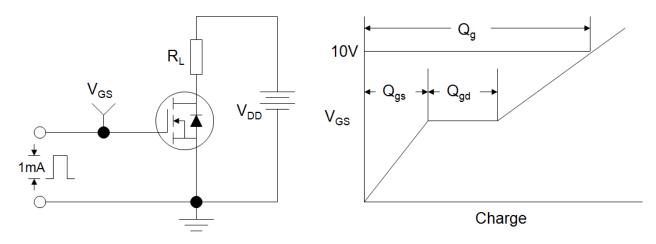


Figure A: Gate Charge Test Circuit and Waveforms

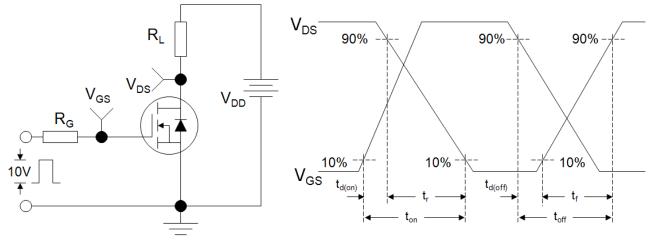


Figure B: Resistive Switching Test Circuit and Waveforms

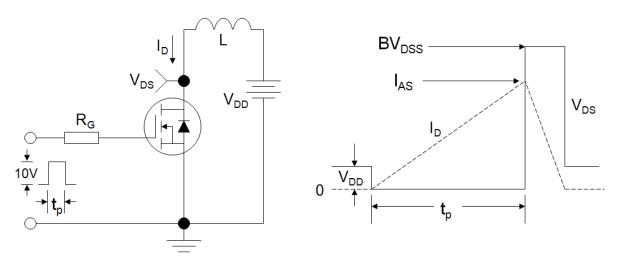
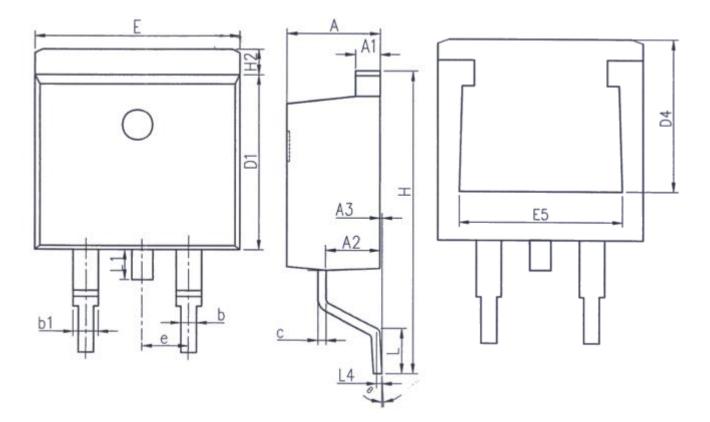


Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms



TO-263(集佳)

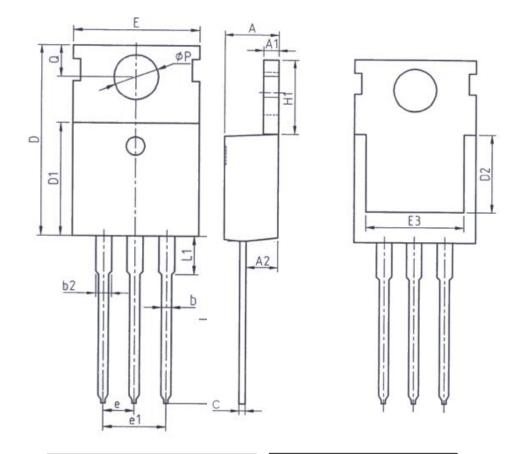


Unit: mm					
Symbol	Min	Nom	Max		
A	4.40	4.50	4.60		
A1	1.25	1.30	1.35		
A2	2.20	2.40	2.60		
A3	0	0.10	0.25		
b	0.76	-	0.89		
b1	1.23	-	1.37		
С	0.47	-	0.60		
D1	9.10	9.20	9.30		
D4	8.00	-	-		

Unit: mm					
Symbol	Min Nom Max				
E	9.80	9.90	10.00		
E5	7.80	-	-		
е	2.54BSC				
Н	14.90 15.30 15.70				
H2	1.17	1.27	1.40		
L	2.00	2.30	2.60		
L1	-	-	1.75		
L4	0.25BSC				
θ	0°		8°		



TO-220(华天)

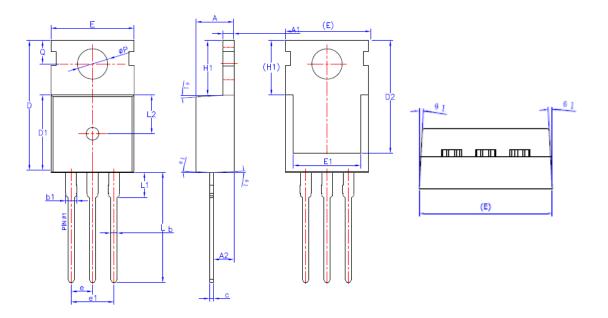


Unit: mm				
Symbol Min. Max.				
Α	4. 37	4.77		
A1	1.25	1.45		
A2	2.20	2.60		
b	0.70	0.95		
b2	1.17	1.47		
С	0.40	0.65		
D	15.10	16. 10		
D1	8.80	9.40		
D2	5.50	-		

Unit: mm					
Symbol	Min. Max.				
E	9.70 10.30				
E3	7.00	-			
e	e 2.54BSC				
e1	5. 08BSC				
H1	6. 25 6. 85				
L	12.75	13.80			
L1	- 3.40				
Ρ	3. 40	3.80			
Q	2.60	3.00			



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SYMBOL	MIN	NOM	MAX	
A	4.40	4.50	4.60	
A1	1.27	1.30	1.33	
A2	2.30	2.40	2.50	
b	0.70	-	0.90	
b1	1.27	-	1.40	
с	0.45	0.50	0.60	
D	15.30	15.70	16.10	
D1	9.10	9.20	9.30	
D2	13.10	-	13.70	
E	9.70	9.90	10.20	
E1	7.80	8.00	8.20	
е	2	2.54BSC		
e1	5.08BSC			
H1	6.30	6.50	6.70	
L	12.78	13.08	13.38	
L1	-	-	3.50	
L2	4.60REF			
øP	3.55	3.60	3.65	
Q	2.73	-	2.87	
θ1	1*	3'	5*	



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